

Low-Dropout Linear Regulator Controller with PGOOD Indication

General Description

The RT9194 is a low-dropout voltage regulator controller with a specific PGOOD indicating scheme, it acts as a power supervisor of the power regulated. The part could drive an external N-Channel MOSFET for various applications accordingly; especially, the part is operated with V_{CC} power ranging from 4.5V to 13.5V. With such a topology, it's with advantages of flexible and cost-effective. The part comes to a small footprint package of SOT-23-6.

Ordering Information

RT9194 □□

Package Type
E : SOT-23-6

Operating Temperature Range
P : Pb Free with Commercial Standard
G : Green (Halogen Free with Commercial Standard)

Note :

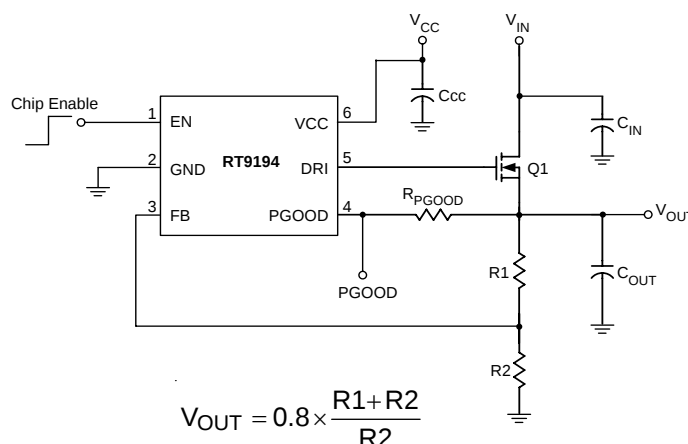
RichTek Pb-free and Green products are :

- ▶RoHS compliant and compatible with the current requirements of IPC/JEDEC J-STD-020.
- ▶Suitable for use in SnPb or Pb-free soldering processes.
- ▶100%matte tin (Sn) plating.

Marking Information

For marking information, contact our sales representative directly or through a RichTek distributor located in your area, otherwise visit our website for detail.

Typical Application Circuit



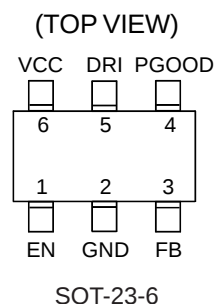
Features

- 4.5V to 13.5V Operation Voltage
- High Accuracy $\pm 2\%$ 0.8V Voltage Reference
- Quick Transient Response
- Power Good Indicator with Delay
- Enable Control
- Compliant with Intel "Grantsdale Chipset Platform Design Guide" Specification
- Small Footprint Package SOT-23-6
- RoHS Compliant and 100% Lead (Pb)-Free

Applications

- Special Designed for Intel® Grantsdale platform FSB_VTT power regulation
- Processor Power-Up Sequencing
- Notebook and laptop PC
- Other Power regulation with Power Good indication.

Pin Configurations



Note : There is no pin1 indicator on top mark for SOT-23-6 type, and pin 1 will be lower left pin when reading top mark from left to right.

Test Circuit

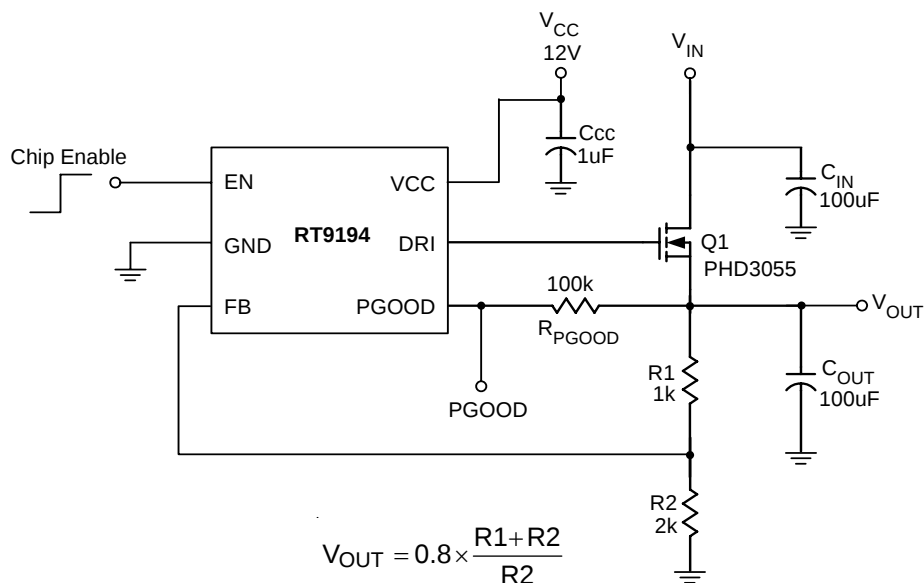


Figure 1. Typical Test Circuit

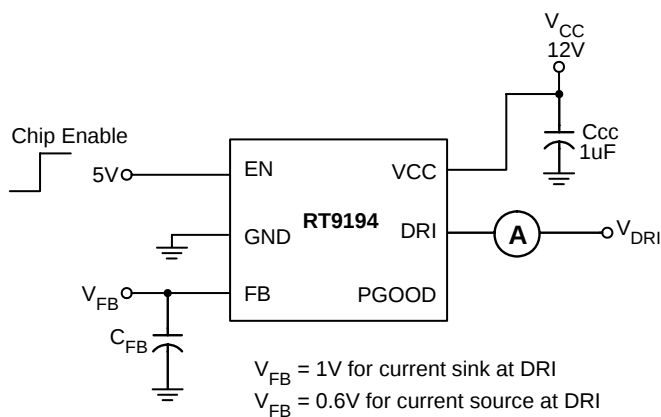
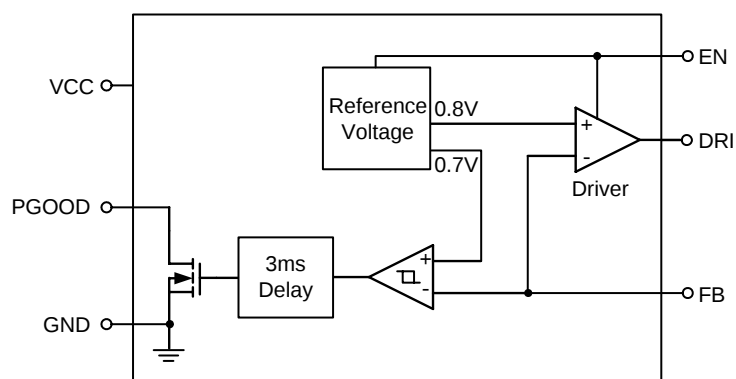


Figure 2. DRI Source/Sink Current Test Circuit

Functional Pin Description

Pin Name	Pin No.	Pin Function
EN	1	Chip Enable (Active High)
GND	2	Ground
FB	3	Output Voltage Feedback
PGOOD	4	Power Good Open Drain Output
DRI	5	Driver Output
VCC	6	Power Supply Input

Function Block Diagram



Absolute Maximum Ratings (Note 1)

• Supply Input Voltage, V_{CC}	15V
• Enable Voltage	7V
• Power Good Output Voltage	7V
• Power Dissipation, P_D @ $T_A = 25^\circ\text{C}$	
SOT-23-6	0.4W
• Package Thermal Resistance	
SOT-23-6, θ_{JA}	250°C/W
• Lead Temperature (Soldering, 10 sec.)	260°C
• Junction Temperature	150°C
• Storage Temperature Range	-65°C to 150°C
• ESD Susceptibility (Note 2)	
HBM (Human Body Mode)	2kV
MM (Machine Mode)	200V

Recommended Operating Conditions (Note 3)

• Supply Input Voltage, V_{CC}	4.5V to 13.5V
• Enable Voltage	0V to 5.5V
• Junction Temperature Range	-40°C to 125°C
• Ambient Temperature Range	-40°C to 85°C

Electrical Characteristics(V_{CC} = 5V/12V, T_A = 25°C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
V _{CC} Operation Voltage Range		V _{CC} input range	4.5	--	13.5	V
POR Threshold		V _{CC} rising	4.0	4.2	4.5	V
POR Hysteresis		V _{CC} falling	--	0.2	--	V
V _{CC} Supply Current		V _{CC} = 12V	--	0.3	0.8	mA
Driver Source Current		V _{CC} = 12V, V _{DRI} = 6V	5	--	--	mA
Driver Sink Current		V _{CC} = 12V, V _{DRI} = 6V	5	--	--	mA
Reference Voltage (V _{FB})		V _{CC} = 12V, V _{DRI} = 5V	0.784	0.8	0.816	V
Reference Line Regulation (V _{FB})		V _{CC} = 4.5V to 15V	--	3	6	mV
Amplifier Voltage Gain		V _{CC} = 12V, no load	--	70	--	dB
PSRR at 100Hz, No Load		V _{CC} = 12V, no load	50	--	--	dB
Power Good						
Rising Threshold		V _{CC} = 12V	--	90	--	%
Hysteresis		V _{CC} = 12V	--	15	--	%
Sink Capability		V _{CC} = 12V @ 1mA	--	0.2	0.4	V
Delay Time		V _{CC} = 12V	1	3	10	ms
Falling Delay		V _{CC} = 12V	--	15	--	us

To be Continued

Parameter		Test Conditions	Min	Typ	Max	Units
Chip Enable						
EN Rising Threshold		V _{CC} = 12V	--	0.7	--	V
EN Hysteresis		V _{CC} = 12V	--	30	--	mV
Standby Current		V _{CC} = 12V, V _{EN} = 0V	--	--	5	uA

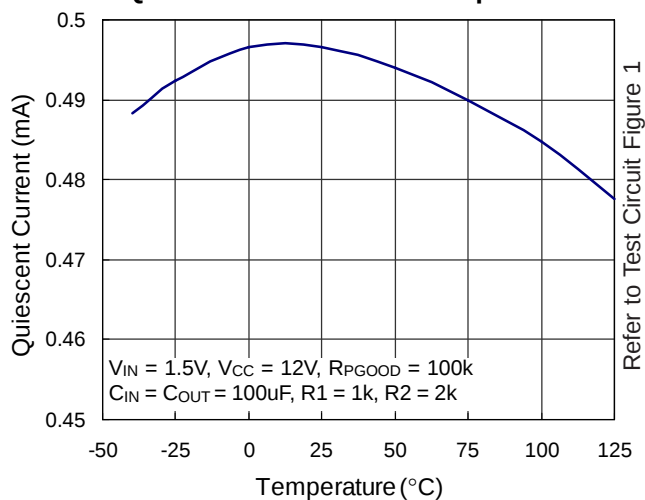
Note 1. Stresses listed as the above "Absolute Maximum Ratings" may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may remain possibility to affect device reliability.

Note 2. Devices are ESD sensitive. Handling precaution recommended.

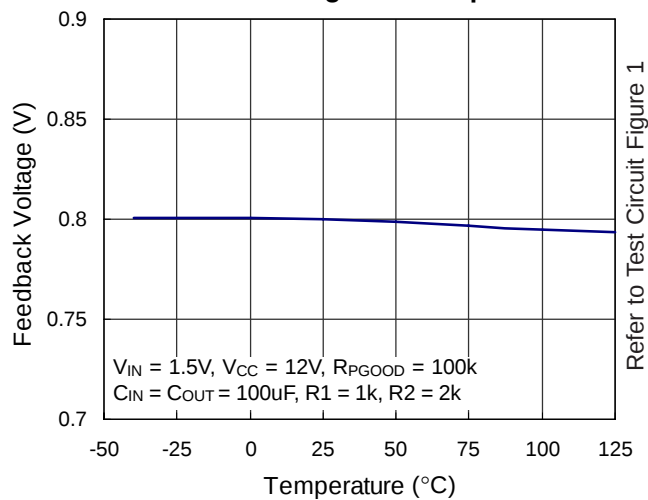
Note 3. The device is not guaranteed to function outside its operating conditions.

Typical Operating Characteristics

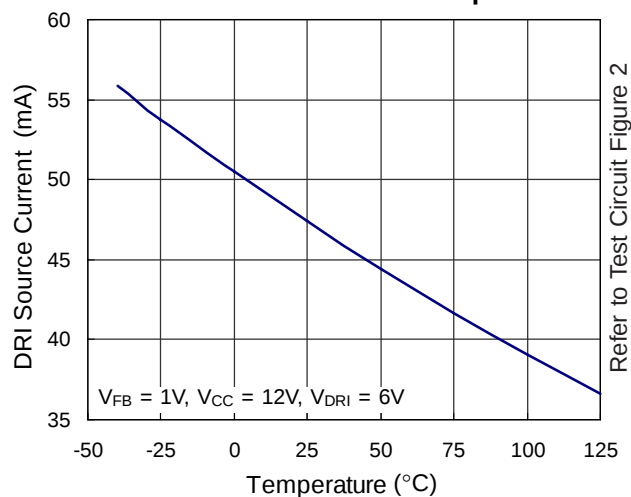
Quiescent Current vs. Temperature



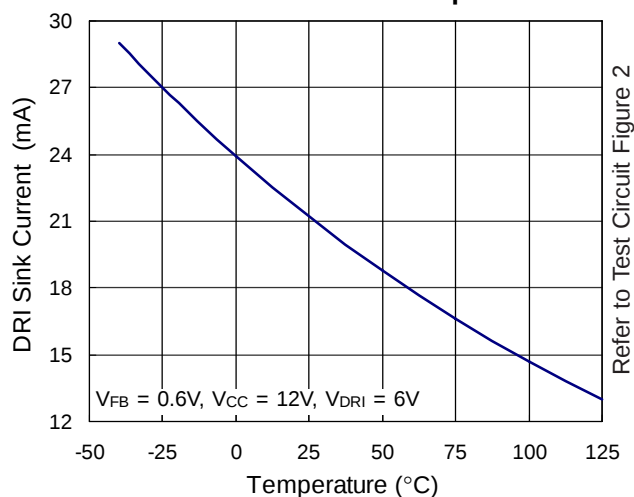
Feedback Voltage vs. Temperature



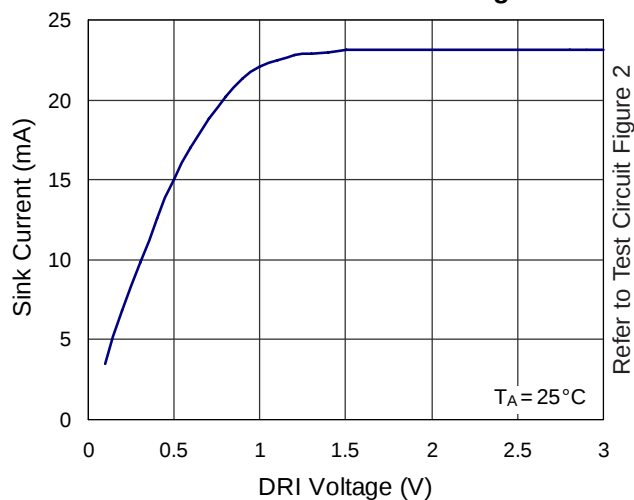
DRI Source Current vs. Temperature



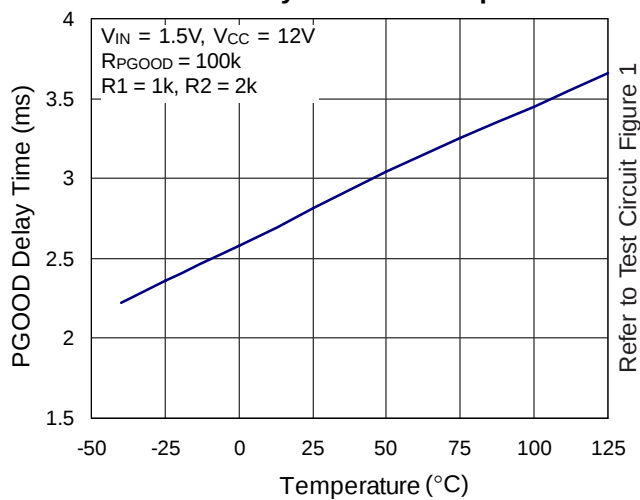
DRI Sink Current vs. Temperature



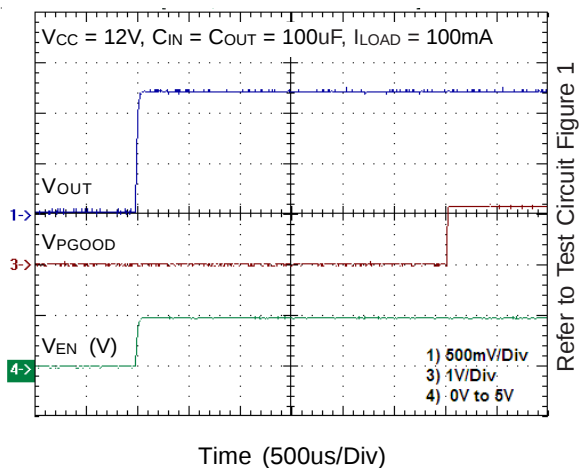
Sink Current vs. DRI Voltage



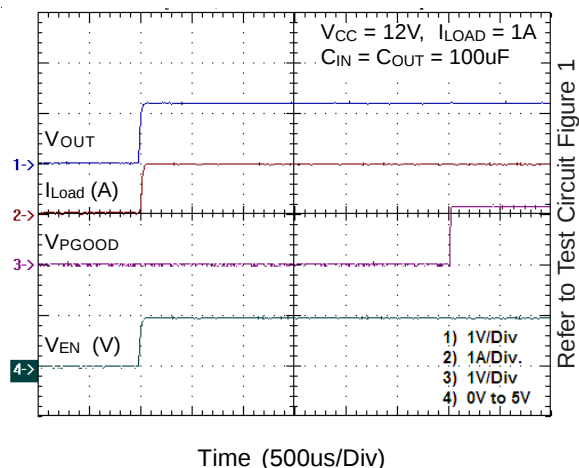
PGOOD Delay Time vs. Temperature



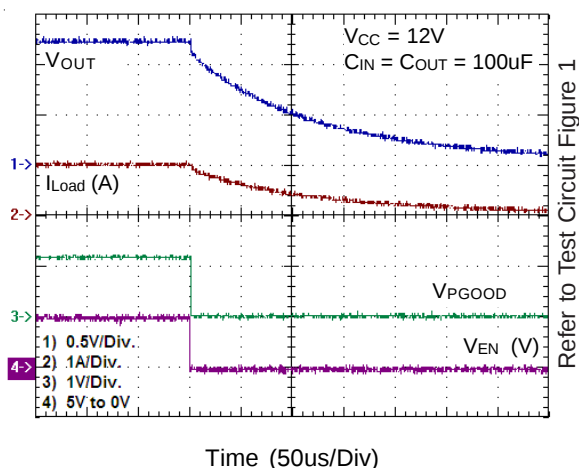
PGOOD Delay Time



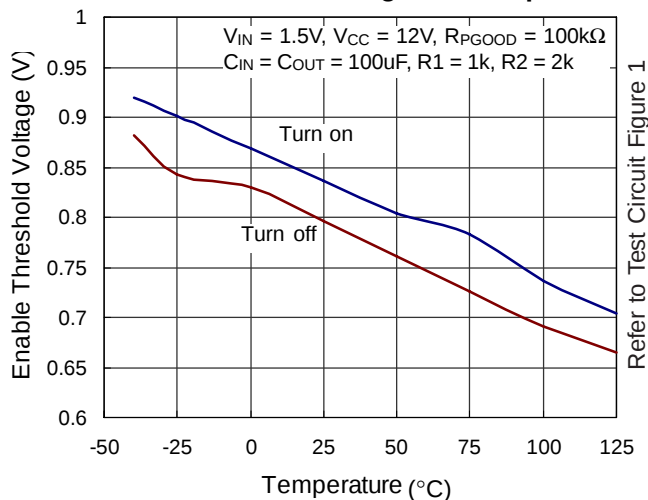
PGOOD Delay Time



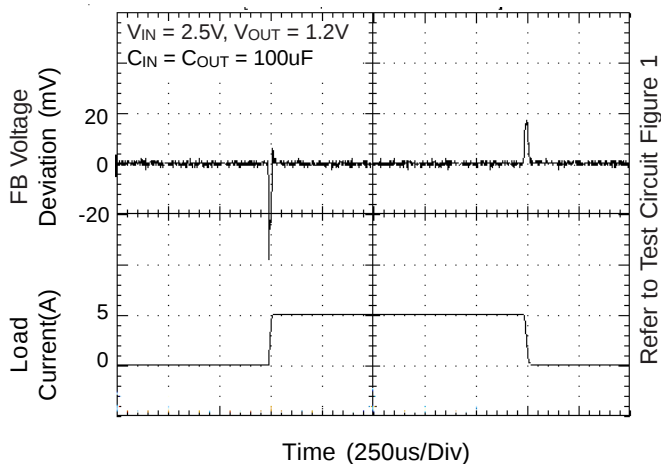
PGOOD Off



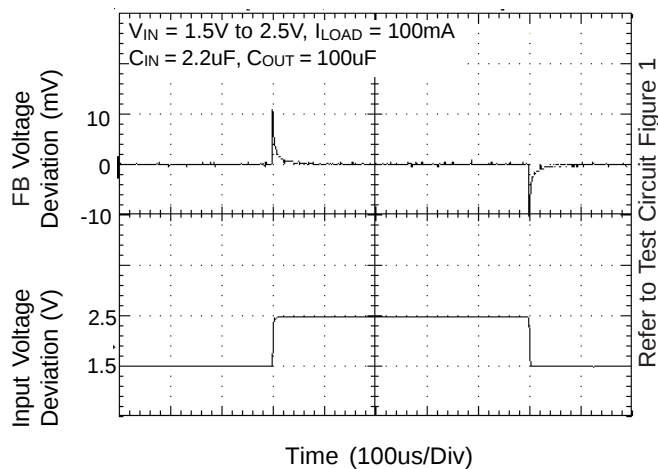
Enable Threshold Voltage vs. Temperature



Load Transient Response



Line Transient Response



Application Information

Capacitors Selection

Careful selection of the external capacitors for RT9194 is highly recommended in order to remain high stability and performance.

Regarding the supply voltage capacitor, connecting a capacitor which is 1 μ F between V_{CC} and ground is a must. The capacitor improves the supply voltage stability to provide chip normally operating.

Regarding the input capacitor, connecting a capacitor which 100 μ F between V_{IN} and ground is recommended to increase stability. With large value of capacitance could result in better performance for both PSRR and line transient response.

When driving external pass element, connecting a capacitor 100 μ F between V_{OUT} and ground is recommended for stability. With larger capacitance can reduce noise and improve load transient response and PSRR.

Output Voltage Setting

The RT9194 develop a 0.8V reference voltage; especially suit for low voltage application. As shown in application circuit, the output voltage could easy set the output voltage by R1 & R2 divider resistor.

Power Good Function

The RT9194 has the power good function with delay. The power good output is an open drain output. Connect a 100k Ω pull up resistor to V_{OUT} to obtain an output voltage. When the output voltage arrive 90% of normal value the power good will output voltage with 3ms delay time.

When the output voltage falling arrive 75% of normal value the power good will turn off with less than 1ms delay time. But, there are two exceptions. One is the enable pull low the power good will turn off quickly. The second is the V_{CC} falling arrive POR value (4V typ.) the power good also will turn off quickly.

Chip Enable Operation

Pull the EN pin low to drive the device into shutdown mode. During shutdown mode, the standby current drops to 5 μ A_(MAX). The external capacitor and load current determine

the output voltage decay rate. Drive the EN pin high to turn on the device again.

Under Voltage Protection

RT9194 equips the V_{OUT} under-voltage (UV) protection function. The UV protection circuits will start monitoring the power status after the PGOOD pin goes high. If the output voltage drops to below 75% of its setting value, the PGOOD and DRI pins will be pulled low and latch RT9194. The UV latch status will be released only when V_{CC} or Enable pin goes low and returns high again, which will also cause RT9194 to re-activate.

MOSFET Selection

The RT9194 are designed to driver external N-Channel MOSFET pass element. MOSFET selection criteria include threshold voltage V_{GS} (V_{TH}), maximum continuous drain current I_D, on-resistance R_{DS(ON)}, maximum drain-to-source voltage V_{DS} and package thermal resistance θ_{JA} .

The most critical specification is the MOSFET R_{DS(ON)}. Calculate the required R_{DS(ON)} from the following formula:

$$NMOSFET R_{DS(ON)} = \frac{V_{IN} - V_{OUT}}{I_{LOAD}}$$

For example, the MOSFET operate up to 2A when the input voltage is 1.5V and set the output voltage is 1.2V, $R_{ON} = (1.5V - 1.2V) / 2A = 150m\Omega$, the MOSFET's R_{ON} have to select lower than 150m Ω . A Philip PHD3055E MOSFET with an R_{DS(ON)} of 120m Ω (typ.) is a close match.

And carry on consider the thermal resistance from junction to ambient θ_{JA} of the MOSFET's package. The power dissipation calculate by :

$$P_D = (V_{IN} - V_{OUT}) \times I_{LOAD}$$

The thermal resistance from junction to ambient θ_{JA} calculate by :

$$\theta_{JA} = \frac{(T_J - T_A)}{P_D}$$

In this example, $P_D = (1.5V - 1.2V) \times 2A = 0.6W$. The PHD3055E's θ_{JA} is 75°C/W for its D-PAK package, which translates to a 45°C temperature rise above ambient. The package provides exposed backsides that directly transfer heat to the PCB board.

PNP Transistor Selection

The RT9194 could driver the PNP transistor to sink output current. PNP transistor selection criteria include DC current gain h_{FE} , threshold voltage V_{EB} , collector-emitter voltage V_{CE} , maximum continues collector current I_C , package thermal resistance θ_{JA} .

For example, the PNP transistor operates sink current up to 0.5A when the input voltage is 1.5V and set the output voltage is 1.2V. As show in Figure 3. A KSB772 PNP transistor, the $V_{CE} = 1.2V$, $V_{BE} = -1V$, $I_C = 0.5A$, $I_B = 0.5/160 = 3.125mA$, when the DRI pin voltage is 0.2V could sink $6.8mA_{(MAX)}$ is a close match.

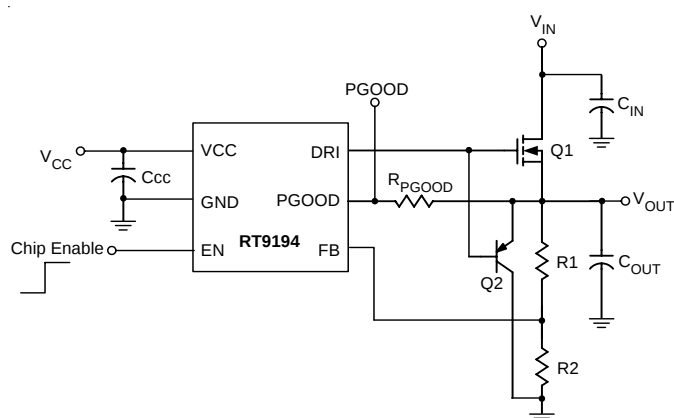


Figure 3

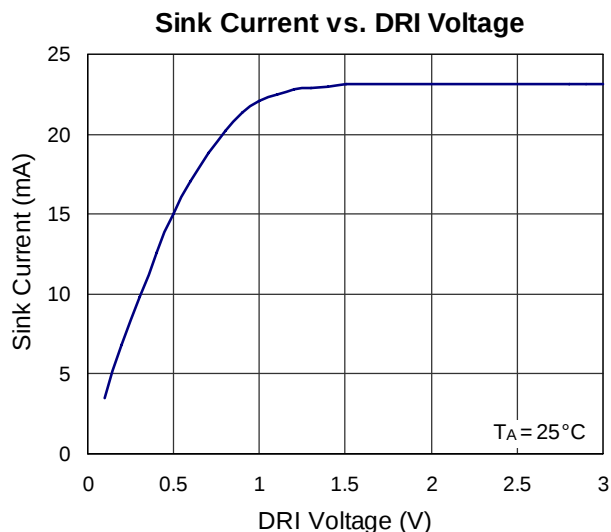


Figure 4

Layout Considerations

There are three critical layout considerations. One is the divider resistors should be located to RT9194 as possible to avoid inducing any noise. The second is capacitors place. The C_{IN} and C_{OUT} have to put at near the NMOS for improve performance. The third is the copper area for pass element. We have to consider when the pass element operating under high power situation that could rise the junction temperature. In addition to the package thermal resistance limit, we could add the copper area to improve the power dissipation. As show in Figure 5 and Figure 6.

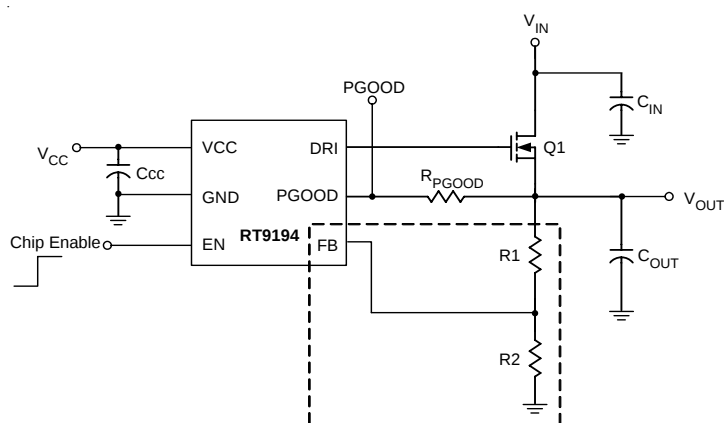


Figure 5

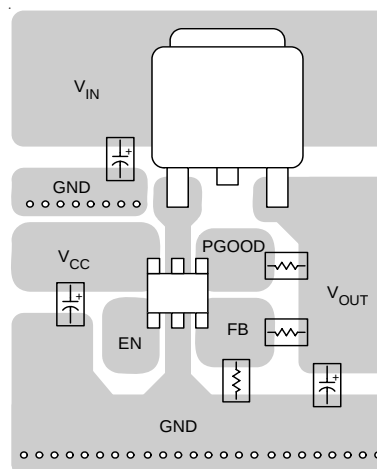
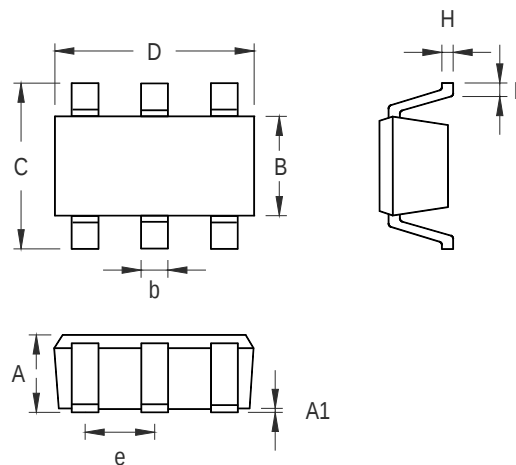


Figure 6

Outline Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.889	1.295	0.031	0.051
A1	0.000	0.152	0.000	0.006
B	1.397	1.803	0.055	0.071
b	0.250	0.560	0.010	0.022
C	2.591	2.997	0.102	0.118
D	2.692	3.099	0.106	0.122
e	0.838	1.041	0.033	0.041
H	0.080	0.254	0.003	0.010
L	0.300	0.610	0.012	0.024

SOT-23-6 Surface Mount Package

Richtek Technology Corporation

Headquarter

5F, No. 20, Taiyuen Street, Chupei City

Hsinchu, Taiwan, R.O.C.

Tel: (8863)5526789 Fax: (8863)5526611

Richtek Technology Corporation

Taipei Office (Marketing)

8F, No. 137, Lane 235, Paochiao Road, Hsintien City

Taipei County, Taiwan, R.O.C.

Tel: (8862)89191466 Fax: (8862)89191465

Email: marketing@richtek.com